



Surface Mount Terminal Blocks

TYPE 971-SLT-SMD

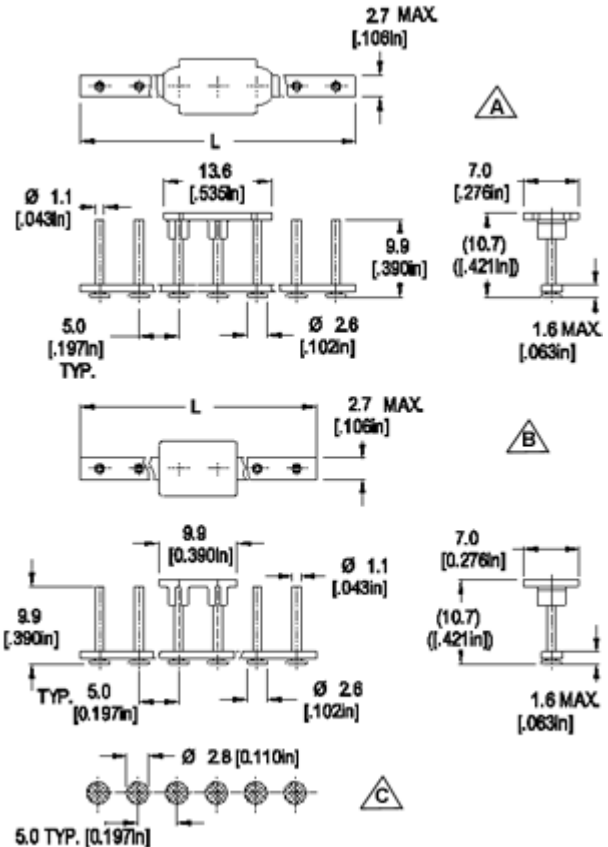
5 mm spacing - 2 to 12 poles



Distributor Stock Check



RoHS WEEE Pb free surface compliant



Description

U.S. Pat.6,224,399B1

- Pinstrip
- Low profile
- Plug-In Direction Perpendicular to PCB and Wire Entrance Parallel to PCB when plugged with 950-NAF-DS, 950-NLFL-DS, 958-NLFL-DS, 950-FL-DS, 950-T-FL-DS, 950-RNF-DS, 115-F-111, 115-F-118 and 115-F-211
- Exceptional pin retention force on SMT
- Typical resistance to horizontal peel off force per 2 poles: 15 kgf (33 lbf), per 6 poles: 28 kgf (61 lbs) (depending on soldering process).

Technical Data

Center to Center Spacing: 5 mm (0.197 in.)

Dimensions: mm (in.)

Length of Connector (L)
 L = No. of Poles x Center to Center Spacing
 (A) Odd numbers of poles
 (B) Even numbers of poles
 (C) PCB Pad layout

Recommended Stencil Thickness: 0.15 mm (0.006 in.)

When locating connector, allow 0.5 mm clearance around it for process-induced variations.

Approval Information

UL File No.E69841
 CSA File No.LR24322

| Rating | Current(A) | Voltage(V) | Application group | AWG |
|--------|------------|------------|-------------------|-----|
| UL | 10 | 300 | B | |
| CSA | 10 | 300 | B | |

Material

Molding: Polyamide 4.6, 30% GF (glass fiber reinforced), self extinguishing UL 94, V-0, color Black

Temperature limits:

Short Time: 260°C (500°F)

Continuous: RTI 105°C (221°F)

Low Limit: -40°C (-40°F)

Comparative Tracking Index: CTI > 250

Oxygen Index Rating: 37 %

Average weight per pole: 0.1 gram per pole,

Solder Pin: Ø 1.1 mm (0.04 in.), Tin plated copper alloy

Item

971-SLT-SMD

Options

- G05: Gold Plating (5 micro inches)
- G30: Gold Plating (30 micro inches)
- S30: Silver Plating (30 micro inches)
- TR: Tape and Reel Assembly
- PCP: Removable Pick Cap

Note: Plated component: solder pin

Ordering Note: This product is currently available in Tape and Reel in 6 poles only. For other configuration, please contact factory.

Accessories

971-SLT-SMD/

POLES:
02 to 12